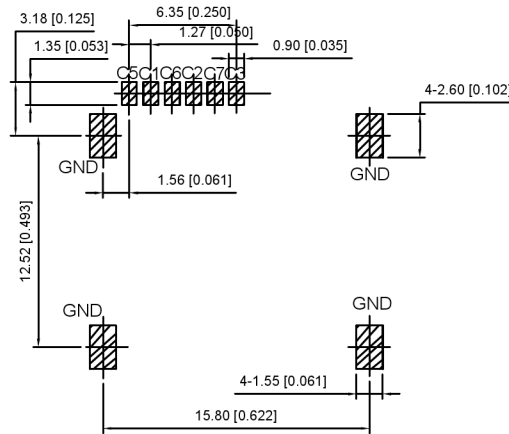


MICRO SIM CARD



- CIRCUT TRACE KEEP OUT AREA
- SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

NOTES:

MATERIAL:

Insulator: High Temperature Thermoplastic,
Contact: Copper Alloy
Shell: STAINLESS

PLATING:

Contact: Plated 30u" Ni Overall , Solder Area: Tin, Contact G/F
Shell: Plated 30u" Ni Overall
Plated G/F Selective Contact Area

Electrical:

Current Rating :0.5mA max.
Voltage Rating :50V DC MAX
Ambient Temperature Range :-20°C~+85°C
Storage Temperature Range :-40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100m_max.
Insulation Resistance:1000M_min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature: 260°C ±5°

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	6	COPPER ALLOY	
①	Housing	1	HI-TEMP_PLASIC UL 94V-0	BLACK

广东星坤科技股份有限公司

ΔX		日期
ΔX		日期
ΔX		日期
MARK		DESCRIPTION

文件工程章

REVISIONS	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
				ANGLAR ±5°
				L ≤ 4 ±0.2
				4 < L ≤ 16 ±0.3
				16 < L ≤ 63 ±0.4
				L > 63 ±0.5

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DSND	SCALE: N/A	MODEL TYPE: SIM CARD CONN
DWN	VIEW:	PART NO.:
CHKD	UNIT: mm/in	DWG NO.:
APPD	SIZE: A4	XKSIM-002-P6
	WEIGHT	SHEET
		1/1
	REVISION	A0